

# Table of Contents



**NXP  
PN548 (65V10)  
Near Field Communication  
Module**

**Basic Functional Analysis**

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## **Table of Contents**

- 1 Introduction**
  - 1.1 Device Naming Conventions Used in this Report
  - 1.2 Device Samples Used for Analysis
  - 1.3 Company Profile
  - 1.4 Executive Summary
  - 1.5 Observed Critical Dimensions
  
- 2 Device Identification**
  - 2.1 iPhone 6 Plus Smartphone Downstream Product
  - 2.2 65V10 Package
  - 2.3 PN548 Die
  - 2.4 PN548 Die Features
  - 2.5 008 Die
  - 2.6 008 Die Features
  
- 3 Process Analysis**
  - 3.1 PN548 Die Cross-Sectional Analysis
  - 3.2 008 Die Cross-Sectional Analysis
  
- 4 Functional Layout Analysis**
  - 4.1 PN548 Die Functional Layout Analysis
  - 4.2 PN548 Die Functional Block Summary
  - 4.3 008 Die Functional Layout Analysis
  - 4.4 008 Die Functional Block Summary
  - 4.5 65V10 NFC package with Pin Number Annotation
  - 4.6 PN548 Die with Pin Number Annotation
  - 4.7 008 Die with Pin Number Annotation
  
- 5 Cost Analysis**
  - 5.1 65V10 Manufacturing Cost Analysis
  
- 6 References**
  
- 7 Statement of Measurement Uncertainty and Scope Variation**

## **About Chipworks**

## List of Figures

- Figure 2.1.1 iPhone 6 Plus Smartphone – Top View
- Figure 2.1.2 iPhone 6 Plus Smartphone – Bottom View
- Figure 2.1.3 iPhone 6 Plus 16 GB Box – Back
- Figure 2.1.4 iPhone 6 and iPhone 6 Plus Smartphone Main PCB – Bottom
- Figure 2.2.1 65V10 NFC Package Photograph – Top View
- Figure 2.2.2 65V10 NFC Package Photograph – Bottom View
- Figure 2.2.3 65V10 NFC Package X-Ray – Plan View
- Figure 2.2.4 65V10 Package X-Ray – Side View
- Figure 2.3.1 PN548 Die Photograph
- Figure 2.3.2 PN548 Die Markings A
- Figure 2.3.3 PN548 Die Markings B
- Figure 2.3.4 PN548 Die Photograph – Delayered to Polysilicon
- Figure 2.4.1 PN548 Die Corner
- Figure 2.4.2 PN548 Minimum Pitch Flip-Chip Bump Pads
- Figure 2.5.1 008 Die Photograph
- Figure 2.5.2 008 Die Markings
- Figure 2.5.3 008 Die Photograph – Delayered to Polysilicon
- Figure 2.6.1 008 Die Corner
- Figure 2.6.2 008 Minimum Pitch Bond Pads
- Figure 3.1.1 PN548 General Structure – Logic
- Figure 3.1.2 PN548 Minimum Metal 2 Pitch
- Figure 3.1.3 PN548 Minimum Contacted Gate Pitch
- Figure 3.1.4 Embedded NOR Flash
- Figure 3.2.1 008 General Structure – Logic
- Figure 3.2.2 008 Minimum Metal 1 Pitch
- Figure 3.2.3 008 Minimum Contacted Gate Pitch
- Figure 3.2.4 Observed Minimum Gate Length Transistor
- Figure 4.1.1 PN548 Die Functional Blocks at the Polysilicon Layer
- Figure 4.3.1 008 Die Functional Blocks at the Polysilicon Layer
- Figure 4.5.1 65V10 NFC Package Photograph with Pin Number Annotation
- Figure 4.6.1 PN548 Die Photograph with Pin Number Annotation
- Figure 4.7.1 008 Die Photograph with Pin Number Annotation

## **List of Tables**

Table 1.2.1 65V10 Component Summary

Table 1.4.1 PN548 Die Summary

Table 1.4.2 008 Die Summary

Table 1.5.1 PN548 Die Observed Critical Dimensions

Table 1.5.2 008 Die Observed Critical Dimensions

Table 4.2.1 PN548 Die Functional Block Summary

Table 4.4.1 008 Functional Block Summary

Table 5.1.1 65V10 Manufacturing Cost Characteristics

Table 5.1.2 PN548 Die Manufacturing Cost Characteristics

Table 5.1.3 008 Die Manufacturing Cost Characteristics

Table 5.1.4 65V10 Manufacturing Costs

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